

KEEP COOL PERFORM BETTER

Honeywell Thermal Interface Materials for Today's Electronics

PRODUCT OVERVIEW GUIDE				
APPLICATION	SOLUTION FAMILIES	PRODUCTS	KEY FEATURES	THERMAL CONDUCTIVITY (W/m·K)
High Reliability Thin Bondline	Phase Change Materials	LTM Series	Paste Only	1.8-2.4
		PCM45F Series	High Reliability	2.0-2.5
		PTM5000 Series	High Reliability	3.5-4.5
		PTM6000 Series	High Reliability	3.5-4.5
		PTM7000 Series	Low TI, High Reliability	6.0-8.5
High Compressibility Gap Filler	Thermal Gap Filler Pads	TGP1200	Cost Effectiveness	1.2
		TGP1500	Cost Effectiveness	1.5
		TGP3000	Low Hardness	3.0
		TGP5000	Low Hardness	5.0
		TGP6000	Low Oil Bleeding	6.0
		TGP8000	Low Oil Bleeding, Low Outgassing, Low Hardness	8.0
		TGP8000HV	High Breakdown Voltage	8.0
		TGP8000LV	Low Volatile	8.0
		HGP10000	High Thermal	10.0
		HGP12	High TC	12.0
	Thermal Putty Pads	TGP2000PT	Extra Soft, Cost Effectiveness	2.5
		TGP3510PT	Extra Soft	3.5
		TGP6000PT	Extra Soft	6.0
		TGP8000PT	Extra Soft	8.0
	Silicone Free Pads	TGP3000SF	Non-silicone	3.0
		TGP8000SF	Non-silicone	8.0
Thermal Conductivity Electrical Isolation	Thermal Insulators	TIP1500	High Breakdown Voltage	1.5
		TIP3500	High Breakdown Voltage	3.5
		TIP5000	High Breakdown Voltage	5.0
Ease of Application Thin Bondline	Thermal Grease	TG2000I	Cost Effectiveness, Electrical Isolation	2.0
		TG2800I	Cost Effectiveness, Electrical Isolation	2.8
		TG3000I	Cost Effectiveness, Electrical Isolation	3.0
		TG3000	Cost Effectiveness	3.0
		TG4000	High TC, Low TI	4.0
		TG5500	High TC, Low TI	5.0
Automation Gap Filler	One-Part Hybrid	HT3000	Thermosetting, reworkable	3.5
		HT3500	Cost Effectiveness	3.5
		HT4500	Printable	4.5
		HT5010	Pre-cure, Low Oil Bleeding	5.0
		HT7000	Pre-cure, Low Oil Bleeding	7.0
		HT9000C	Thermosetting, Reworkable, High TC	9.0
		HT10000	Pre-cure, Low Oil Bleeding	10.0
	Two-Part Hybrid	HLT1800	Low density, Cost Effectiveness	1.8
		HLT2000	Cost Effectiveness	2.0
		HLT3000	Easy to Dispense Printable	3.0
		HLT3500	Cost Effectiveness	3.5
		HLT3500LV	Low Volatile	3.5
		HLT7000	High Reliability, Easy to Dispense	7.0
		HLT10000	High Reliability, Easy to Dispense	10.0

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For More Information

visit <https://industrial.honeywell.com/us/en/products/electronic-materials>

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